

FBT250 Test Die

The Kokomo Semiconductor FBT250 test chip is designed with I/O pads on 18 mil (457.2 micron) pitch located on the peripheral of the die. The 0.25-inch by 0.25-inch FBT250 die contains 48 pads giving 24 daisy chain pairs.



➤ IC Fab Information

- Wafer size 5-inch (125 mm)
- Die thickness 600-650 microns
- Metal thickness 17k angstroms
- Metal composition Al/Cu/Si (98/1/1)
- Passivation thickness 10k angstroms
- Passivation type Nitride

➤ Die Sizes Available

- .250" x .250"

➤ Options Available

- 1) Five-inch wafer, no bumps, nitride passivation, 102-micron circular passivation openings (diagram 1)
- 2) Five-inch wafer, FOC bump, 63Sn/37Pb solder, UBM diameter – 178 microns, bump height –140 microns (diagram 3)

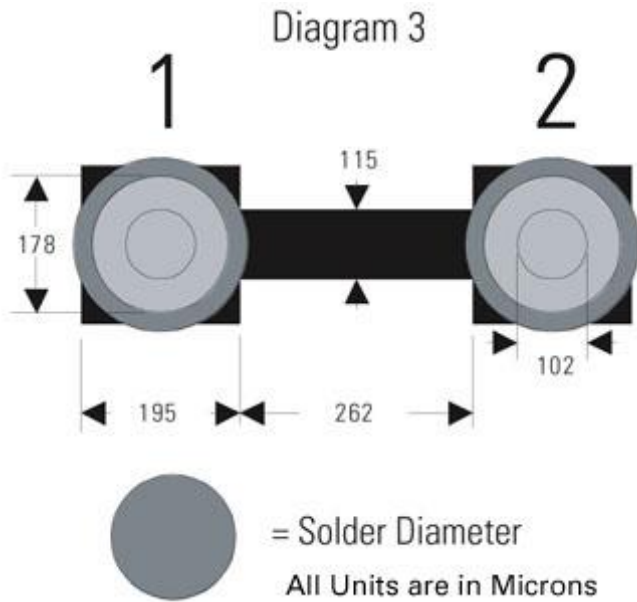
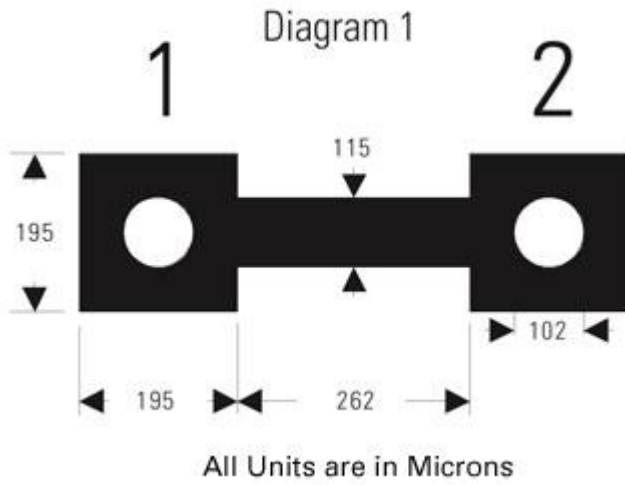
Note: Lead Free solder composition available upon request.

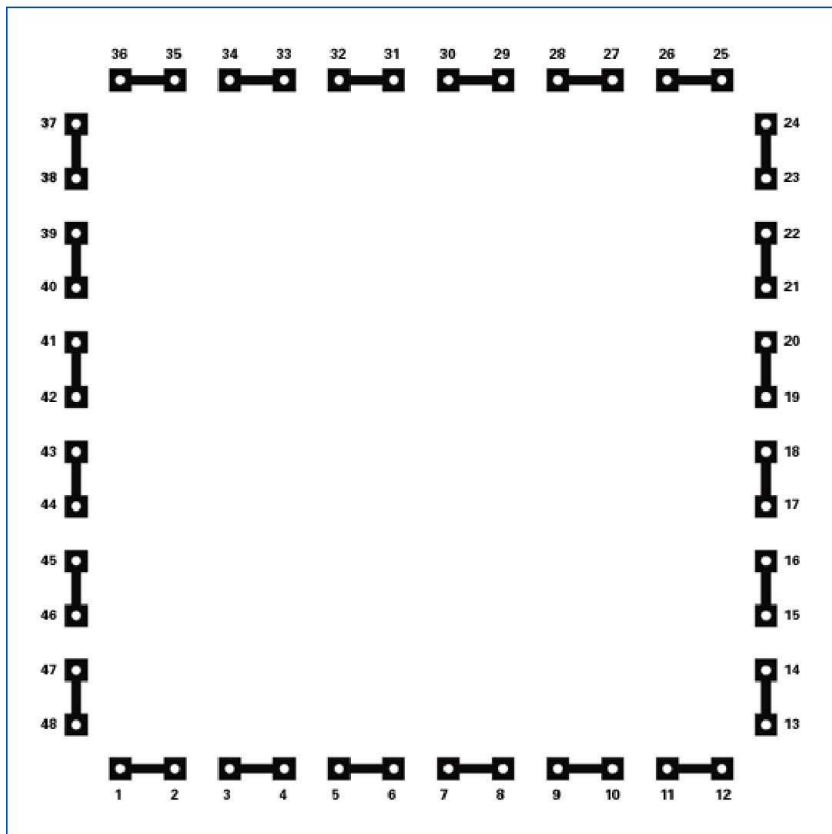
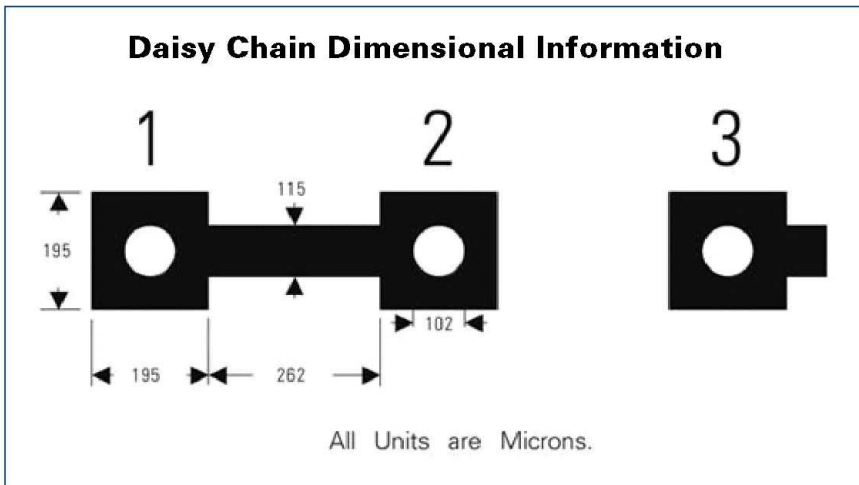
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GM Components Holdings, LLC

FBT250 Test Die





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FBT250 / X,Y Coordinates .250-Inch X .250-Inch Die Sizes (0,0) is located at the center of the die.							
Micron				Micron			
PIN#	NAM E	X	Y	PIN#	NAM E	X	Y
1	Pin1	-2514.6	-2974.8	25	Pin25	2514.6	2974.8
2	Pin2	-2057.4	-2974.8	26	Pin26	2057.4	2974.8
3	Pin3	-1600.2	-2974.8	27	Pin27	1600.2	2974.8
4	Pin4	-1143	-2974.8	28	Pin28	1143	2974.8
5	Pin5	-685.8	-2974.8	29	Pin29	685.8	2974.8
6	Pin6	-228.6	-2974.8	30	Pin30	228.6	2974.8
7	Pin7	228.6	-2974.8	31	Pin31	-228.6	2974.8
8	Pin8	685.8	-2974.8	32	Pin32	-685.8	2974.8
9	Pin9	1143	-2974.8	33	Pin33	-1143	2974.8
10	Pin10	1600.2	-2974.8	34	Pin34	-1600.2	2974.8
11	Pin11	2057.4	-2974.8	35	Pin35	-2057.4	2974.8
12	Pin12	2514.6	-2974.8	36	Pin36	-2514.6	2974.8
13	Pin13	2974.8	-2514.6	37	Pin37	-2974.8	2514.6
14	Pin14	2974.8	-2057.4	38	Pin38	-2974.8	2057.4
15	Pin15	2974.8	-1600.2	39	Pin39	-2974.8	1600.2
16	Pin16	2974.8	-1143	40	Pin40	-2974.8	1143
17	Pin17	2974.8	-685.8	41	Pin41	-2974.8	685.8
18	Pin18	2974.8	-228.6	42	Pin42	-2974.8	228.6
19	Pin19	2974.8	228.6	43	Pin43	-2974.8	-228.6
20	Pin20	2974.8	685.8	44	Pin44	-2974.8	-685.8
21	Pin21	2974.8	1143	45	Pin45	-2974.8	-1143
22	Pin22	2974.8	1600.2	46	Pin46	-2974.8	-1600.2
23	Pin23	2974.8	2057.4	47	Pin47	-2974.8	-2057.4
24	Pin24	2974.8	2514.6	48	Pin48	-2974.8	-2514.6

The test die offered on this web site are to be used to characterize assembly processes and materials. Applying the data from the test die to a functional system is the responsibility of the user. Kokomo Semiconductor makes no warranty, express or implied including the implied warranties of merchantability and fitness for a particular purpose, that the user's system designed using that data will perform as intended by the user.